



60V N-Channel Enhancement Mode MOSFET - ESD Protected

Voltage

60 V

Current

250mA

Features

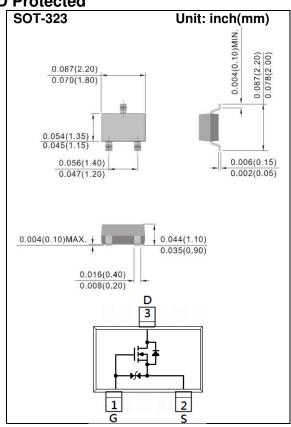
- $R_{DS(ON)}$, $V_{GS}@10V$, $I_{D}@500mA<3\Omega$
- R_{DS(ON)}, V_{GS}@4.5V, I_D@200mA<4Ω
- Advanced Trench Process Technology
- High Density Cell Design For Ultra Low On-Resistance
- Very Low Leakage Current In Off Condition
- Specially Designed for Battery Operated Systems, Solid-State Relays Drivers: Relay, Displays, Memories, etc
- ESD Protected 2KV HBM
- AEC-Q101 qualified
- Lead free in compliance with EU RoHS 2.0
- Green molding compound as per IEC 61249 standard

Mechanical Data

• Case: SOT-323 Package

• Terminals : Solderable per MIL-STD-750, Method 2026

• Approx. Weight: 0.0002 ounces, 0.005 grams



Maximum Ratings and Thermal Characteristics (T_A=25°C unless otherwise noted)

PARAMETER		SYMBOL	LIMIT	UNITS	
Drain-Source Voltage		V _{DS}	60	V	
Gate-Source Voltage		V_{GS}	<u>+</u> 20		
Continuous Drain Current		I _D	250	mA	
Pulsed Drain Current		I _{DM}	1000		
Power Dissipation	T _a =25°C	P _D	350	mW	
	Derate above 25°C		2.8	mW/°C	
Operating Junction and Storage Temperature Range		T_{J} , T_{STG}	-55~150	O°	
Typical Thermal Resistance					
- Junction to Ambient (Note 3)		$R_{\theta JA}$	357	°C/W	





Electrical Characteristics (T_A=25°C unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS
Static						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V,I _D =10uA V _{DS} =V _{GS} , I _D =250uA	60	-	-	V
Gate Threshold Voltage	$V_{GS(th)}$		1	-	2.5	
Drain-Source On-State Resistance	R _{DS(on)}	$V_{GS}=10V,I_D=500mA$	-	-	3	Ω
		V_{GS} =4.5V, I_D =200mA	-	-	4	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V,V _{GS} =0V V _{GS} = <u>+</u> 20V,V _{DS} =0V	-	-	1	uA
Gate-Source Leakage Current	I_{GSS}		-	-	<u>+</u> 10	
Forward Transconductance	g_{fs}	V _{DS} =15V, I _D =250mA	100	-	-	mS
Dynamic (Note 5)						
Total Gate Charge	Q_g	V_{DS} =15V, I_{D} =250mA, V_{GS} =5V (Note 1,2)	-	0.8	-	nC
Gate-Source Charge	Q_gs		-	0.35	-	
Gate-Drain Charge	Q_gd		-	0.2	-	
Input Capacitance	Ciss	V _{DS} =25V, V _{GS} =0V, f=1MHZ	-	24	-	pF
Output Capacitance	Coss		-	13	-	
Reverse Transfer Capacitance	Crss		-	8	-	
Turn-On Delay Time	td _(on)	$V_{DD}{=}30V,\ I_{D}{=}200mA,$ $V_{GS}{=}10V,$ $R_{G}{=}10\Omega^{(Note\ 1,2)}$	-	3	-	
Turn-On Rise Time	tr		-	19	-	ns
Turn-Off Delay Time	td _(off)		-	15	-	
Turn-Off Fall Time	tf		-	23	-	
Drain-Source Diode						
Maximum Continuous Drain-Source			-	-	250	mA
Diode Forward Current	I _S					
Diode Forward Voltage	V_{SD}	I _S =200mA, V _{GS} =0V	-	0.82	1.3	V

NOTES:

- 1. Pulse width<a>300us, Duty cycle<a>2%.
- 2. Essentially independent of operating temperature typical characteristics.
- 3. Rejah is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins mounted on a 1 inch FR-4 with 2oz. square pad of copper.
- 4. The maximum current rating is package limited.
- 5. Guaranteed by design, not subject to production testing.





TYPICAL CHARACTERISTIC CURVES

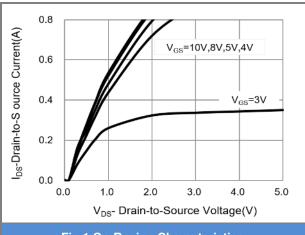


Fig.1 On-Region Characteristics

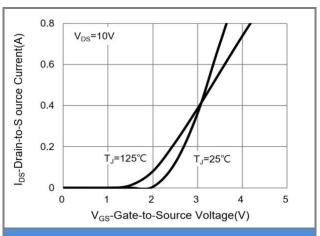


Fig.2 Transfer Characteristics

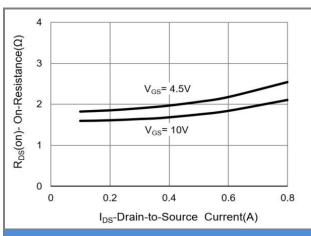


Fig.3 On-Resistance vs. Drain Current

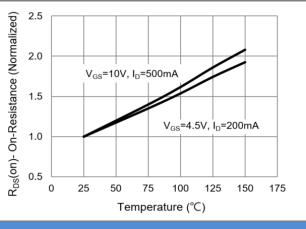


Fig.4 On-Resistance vs. Junction temperature

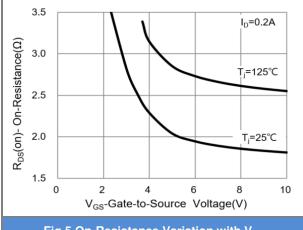


Fig.5 On-Resistance Variation with V_{GS}

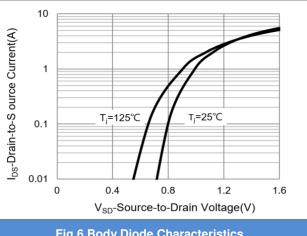


Fig.6 Body Diode Characteristics





TYPICAL CHARACTERISTIC CURVES

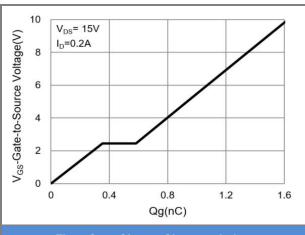


Fig.7 Gate-Charge Characteristics

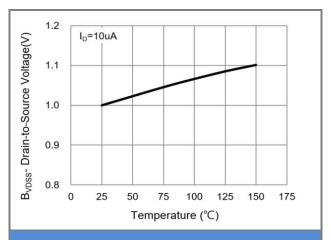


Fig.8 Breakdown Voltage Variation vs. Temperature

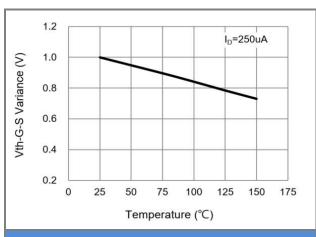


Fig.9 Threshold Voltage Variation with Temperature

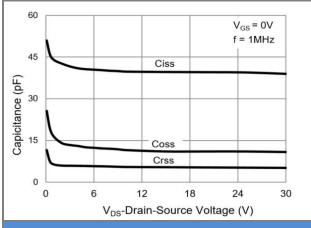


Fig.10 Capacitance vs. Drain-Source Voltage

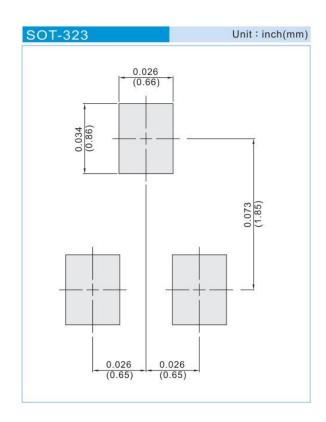




Part No Packing Code Version

Part No Packing Code	Package Type	Packing Type	Marking	Version
2N7002KW-AU_R1_000A1	SOT-323	3K pcs / 7" reel	K72	Halogen free

Mounting Pad Layout







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